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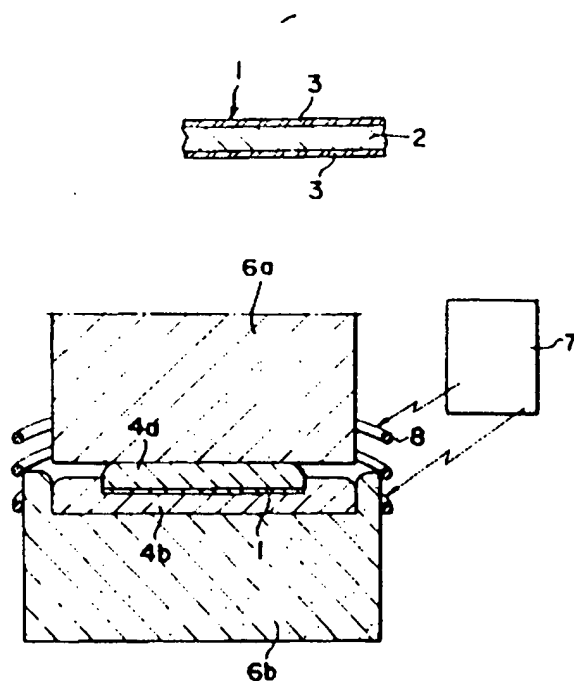
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TITLE : BONDING METHOD AND BONDED PRODUCT



ABSTRACT : PURPOSE: To bond a material efficiently and firmly in a short time, by inserting a bonding medium prepared by coating both surfaces of a metallic film with a heat-sensitive adhesive between a pair of adherends under pressed conditions, applying a high-frequency induction current thereto, and melting the adhesive under heating.

CONSTITUTION: Both surfaces of a metallic film 2, preferably an aluminum film having a thickness of  $50\mu$ , are coated with a heat-sensitive 3, preferably ethylene-vinyl acetate copolymer in a film thickness preferably  $\leq 10\mu$  to give a film-like bonding medium 1. The resultant medium 1 is then inserted between a pair of molded synthetic resin articles (4a) and (4b), held and placed between jigs (6a) and (6b) and pressed, and the molded synthetic resin article (4a) is then lightly pressed to the other molded article (4b). A coil 8 is wound around the articles (4a) and (4b) and jigs (6a) and (6b) to supply a high-frequency current to the coil 8. A high-frequency current is then generated in the metallic film 2 to heat and melt the adhesive 3 and bond the molded articles (4a) and (4b) to each other.

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